PC Web Site for Information on IPC-1752 Standard Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information	This document is a declaration of the substances within the manufacturer l level parts, the declaration encompasses all lower level materials for which	ed item. Note: if the item is an assembly with I he manufacturer has engineering responsibility
Company name* Company unique ID Unique ID Authority Response Date* 2025-07-03 Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards Product-Env-Stewar	pe * Declaration Class * te Class 6 - RoHS Yes/No, Homogeneous Materials	d Mfg Information
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Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Product-Env-Stewards@onsemi.com Terminal Plating / Grid Array Material Proccess Information Terminal Plating / Grid Array Material Proccess Information Terminal Plating / Grid Array Material Proccess Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Proccess metal (e.g. Ag,Au, NiPdAu) (no CU Alloy 4 245 C 30 seconds 3	Unique ID Authority Re	ponse Date*
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Title - Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM NOIX1SE016KB-LTI XGS16M, 24port, Color_CRA_0D Z025-07-03 TA1 Z074.87 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy Title - Representative* Phone - Representative* Email - Representative* Weight* UOM Annufacturing Site Weight* UOM Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy 4 245 C 30 seconds 3	Phone - Contact*	ail - Contact*
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	ISL Rating Peak Process Body Temperature Max Time at Peak Ter	perature Number of Reflow Cycles
	245 C 30	econds 3
Comments		

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	406.14	mg		Misc.	proprietary data		1.5433	mg
			Supplier	Silicon (Si)	7440-21-3		400.5759	mg
			Supplier	Aluminum (Al)	7429-90-5		4.0208	mg
Die Attach Epoxy	83.58	mg	Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		62.685	mg
			Supplier	Imidazole Addition	68490-66-4		2.5074	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		12.537	mg
			Supplier	Silica (SiO2)	14464-46-1		5.8506	mg
Imaging Lens	865.32	mg	Supplier	Sulfur (S)	7704-34-9		4.3266	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		43.266	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		43.266	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		43.266	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		43.266	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		43.266	mg
Lid Attach			Supplier	Potassium Monoxide (K2O)	12136-45-7		43.266	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		601.3974	mg
	7.96	mg	Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		0.398	mg
			Supplier	2,3-epoxypropyl-trimethoxysilan	2530-83-8		0.398	mg
			Supplier	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6		5.97	mg
			Supplier	Inorganic filler	7727-43-7, 14807- 96-6		1.194	mg
Mold Compound-Black Substrate	377.95	mg		Phenolic Resin	proprietary data		56.6925	mg
			Supplier	Oxirane	39817-09-9		56.6925	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		11.3385	mg
			Supplier	Carbon Black (C)	1333-86-4		3.7795	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		241.888	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		7.559	mg
	331.71	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		70.3225	mg
			Supplier	Inorganic filler	Proprietary Data		43.3877	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		4.3454	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.0615	mg
			Supplier	Acetophenone Derivative	Proprietary Data		6.5015	mg

			Supplier	Carbon Black (C)	1333-86-4	1.0946	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	1.0946	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	13.003	mg
			Supplier	Copper (Cu)	7440-50-8	157.2969	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	33.6022	mg
Wire Bond - Au	2.21	mg	Supplier	Gold (Au)	7440-57-5	2.21	mg